



**Model VG101MKII**

No. of Spindle	: 1
No. of Vacuum chuck	: 1
Spindle Motor	: 2.2 Kw
Grinding Mode	: Gauge/ NC
Work spindle Motor	: 1.5 Kw
Wafer size to grind	: 4/5/6 & 8"
Bearing type	: Air (both)

**Semi-Automatic Wafer Grinder for Small batch or R&D**  
**Suitable for Si, SOI, GaAs, InP, Si, Ge and other materials**

**Precision Back Grinder**  
**Model VG101MKII**

**Okamoto Corporation**

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## FEATURES

Model VG101MKII precision grinder is designed to meet R & D purpose for all kind of materials with the increasingly tighter geometric and surface finish requirements. This low cost semi-automatic grinder can easily achieve a total thickness variation (TTV) of less than 1 $\mu$ m.

## SPECIFICATIONS

Maximum wafer-machining diameter of wafer	Ø8" (universal sizes also available)
Grinding Spindle: Bearing type Motor Rapid feed speed Grind feed speed	Air bearing, maximum 3600 rpm 2.2 kw, 4P, high frequency motor 100 mm/min 1 to 999 $\mu$ m/min
Grinding wheel size	Ø250 (mm)
Work spindle Bearing type	Air Bearing, 1 to 999 rpm
Automatic Sizing Device: Wafer thickness measuring system Wafer minimum setting size Wafer size display range NC mode	2 point contact in-process gauge 1 $\mu$ m $\pm$ 1000 Can be grind 140mm
Footprint ( L x W x H )	52" x 45" x 69"
Control Cabinet CRT Display Programming method Vacuum Pump Unit	Mounted on the main body 9" color LCD screen Keyboard 1.5 kw motor, 40 Torrs Exhaust 40 m <sup>3</sup> /hr Coolant (city) water 5 liter/min
Utilities: Electric Power Cutting Water Consumption Cleaning Water Consumption Coolant water (city water) Air consumption (dry air)	3P, 200V, 15KVA 12 to 15 liter/min 4 liter/cycle 5 liter/min (for vacuum pump) 60 N liter/min (5kg/cm <sup>2</sup> )
Grinding Accuracy: Wafer thickness variation Wafer to wafer thickness Roughness	Ø6" = 0.8 $\mu$ m or less, Ø8" = 1.0 $\mu$ m or less Ø6" = 0.8 $\mu$ m or less, Ø8" = 1.0 $\mu$ m or less Rmax = 0.1 $\mu$ m or less

Specifications subject to change without notice.